

WHAT IS CLAIMED IS:

1. A high-frequency circuit board unit comprising:

a circuit board including a ground electrode and a terminal electrode; and

a semiconductor device mounted on said circuit board, including a high-frequency signal terminal for sending and receiving a high-frequency signal to and from said terminal electrode of said circuit board,

5 wherein at least one of said terminal electrode of said circuit board and said high-frequency signal terminal of said semiconductor device is connected to said ground electrode of said circuit board for conducting direct current.

2. A high-frequency circuit board unit according to claim 1, further comprising a passive impedance circuit device mounted on said circuit board and connected between said high-frequency signal terminal and said terminal electrode,

wherein one of said high-frequency signal terminal and said terminal electrode is connected to said ground electrode for conducting direct current via said passive impedance circuit device.

3. A high-frequency circuit board unit according to claim 1, further comprising a passive impedance circuit device mounted on said circuit board and connected between said high-frequency signal terminal and said terminal electrode,

wherein both said high-frequency signal terminal and said terminal electrode are

connected to said ground electrode for conducting direct current via said passive impedance circuit device.

4. A high-frequency circuit board unit according to one of claims 2 and 3, wherein said passive impedance circuit device is formed on a dielectric substrate having a dielectric constant higher than that of both said circuit board and said semiconductor device.

5. A high-frequency circuit board unit according to one of claims 2 and 3, wherein said semiconductor device is bump-mounted on said circuit board.

6. A high-frequency circuit board unit according to any one of claims 1 to 3, further comprising an additional terminal other than said high-frequency signal terminal on said semiconductor device, and an electrostatic protecting diode connected to said additional terminal.

7. A high-frequency module comprising said high-frequency circuit board unit set forth in any one of claims 1 to 3, further comprising an additional component mounted on said circuit board, a cover on said circuit board, and said terminal electrode being disposed externally of said cover.

8. An electronic apparatus comprising said high-frequency module set forth in claim 7.

9. An electronic apparatus comprising said high-frequency circuit board unit set forth in any one of claims 1 to 3.

10. A manufacturing method for a high-frequency circuit board unit, comprising the steps of:

mounting, on a circuit board including a ground electrode and a terminal electrode, a passive impedance circuit device, at least one terminal of which is connected to said ground electrode for conducting direct current, in such a manner that said at least one terminal is connected to said terminal electrode; and

mounting a semiconductor device including a high-frequency signal terminal on said circuit board in such a manner that said high-frequency signal terminal is connected to the other terminal of said passive impedance circuit device.

11. A manufacturing method for a high-frequency circuit board unit according to claim 10, wherein said passive impedance circuit device and said semiconductor device are bump-mounted on said circuit board.

12. A manufacturing method according to claim 10, wherein said at least one terminal of said passive impedance circuit device is connected to said ground electrode after said semiconductor device is mounted on said circuit board.

13. A manufacturing method according to claim 12, wherein said at least one terminal of said passive impedance circuit device is connected to said ground electrode before said high-frequency signal terminal is connected to said other terminal of said passive impedance circuit device.

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